



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20160721003
Datasheet for LMZ1*, LMZ2*, WPMDH1*
Information Only**

Date: 7/22/2016
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes detailed in this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMZ10503TZE-ADJ/NOPB	null
LMZ10505TZE-ADJ/NOPB	null
LMZ14201HTZX/NOPB	null
LMZ10505TZ-ADJ/NOPB	null
LMZ12001TZ-ADJ/NOPB	null
LMZ12001TZE-ADJ/NOPB	null
LMZ12002TZ-ADJ/NOPB	null
LMZ12003TZ-ADJ/NOPB	null
LMZ14201HTZ/NOPB	null
LMZ14203TZ-ADJ/NOPB	null
LMZ23605TZE/NOPB	null
LMZ12002TZE-ADJ/NOPB	null
LMZ14202TZ-ADJ/NOPB	null
LMZ14202TZE-ADJ/NOPB	null
LMZ14203TZE-ADJ/NOPB	null
LMZ10503TZ-ADJ/NOPB	null
LMZ14202HTZ/NOPB	null
LMZ14203HTZ/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160721003		PCN Date:	7/22/2016	
Title:	Datasheet for LMZ1*, LMZ2*, WPMDH1*				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Change Type:					
☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process
Notification Details					
Description of Change:					
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The last item in the Power Module SMT Guidelines below has been included in the various applicable datasheets. The additional information is included in Power Module SMT Guidelines section of each applicable datasheet. Power Module SMT Guidelines The recommendations below are for a standard module surface mount assembly • Land Pattern – Follow the PCB land pattern with either soldermask defined or non-soldermask defined pads • Stencil Aperture – For the exposed die attach pad (DAP), adjust the stencil for approximately 80% coverage of the PCB land pattern – For all other I/O pads use a 1:1 ratio between the aperture and the land pattern recommendation • Solder Paste – Use a standard SAC Alloy such as SAC 305, type 3 or higher • Stencil Thickness – 0.125 to 0.15mm • Reflow - Refer to solder paste supplier recommendation and optimized per board size and density • Maximum number of reflows allowed is one The datasheet revision has changed. The full datasheet may be reviewed by manufacturing part number at the link provided below. http://www.ti.com/					
Reason for Change:					
To more accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.					
Changes to product identification resulting from this PCN:					
None.					

Product Affected:			
LMZ10503EXTTZ/NOPB	LMZ12002EXTTZE/NOPB	LMZ14201TZ-ADJ/NOPB	LMZ22005TZ/NOPB
LMZ10503EXTTZE/NOPB	LMZ12002EXTTZ/NOPB	LMZ14201TZE-ADJ/NOPB	LMZ22005TZE/NOPB
LMZ10503EXTTZ/NOPB	LMZ12002TZ-ADJ/NOPB	LMZ14201TZ-ADJ/NOPB	LMZ22005TZ/NOPB
LMZ10503TZ-ADJ/NOPB	LMZ12002TZE-ADJ/NOPB	LMZ14202EXTTZ/NOPB	LMZ22008TZ/NOPB
LMZ10503TZE-ADJ/NOPB	LMZ12002TZ-ADJ/NOPB	LMZ14202EXTTZE/NOPB	LMZ22008TZE/NOPB
LMZ10503TZ-ADJ/NOPB	LMZ12003EXTTZ/NOPB	LMZ14202EXTTZ/NOPB	LMZ22010TZ/NOPB
LMZ10504EXTTZ/NOPB	LMZ12003EXTTZE/NOPB	LMZ14202HTZ/NOPB	LMZ22010TZE/NOPB
LMZ10504EXTTZE/NOPB	LMZ12003EXTTZ/NOPB	LMZ14202HTZ/NOPB	LMZ23603TZ/NOPB
LMZ10504EXTTZ/NOPB	LMZ12003TZ-ADJ/NOPB	LMZ14202HTZ/NOPB	LMZ23603TZE/NOPB
LMZ10504TZ-ADJ/NOPB	LMZ12003TZE-ADJ/NOPB	LMZ14202TZ-ADJ/NOPB	LMZ23603TZ/NOPB
LMZ10504TZE-ADJ/NOPB	LMZ12003TZ-ADJ/NOPB	LMZ14202TZE-ADJ/NOPB	LMZ23605TZ/NOPB
LMZ10504TZ-ADJ/NOPB	LMZ12008TZ/NOPB	LMZ14202TZ-ADJ/NOPB	LMZ23605TZE/NOPB
LMZ10505EXTTZ/NOPB	LMZ12008TZE/NOPB	LMZ14203EXTTZ/NOPB	LMZ23605TZ/NOPB
LMZ10505EXTTZE/NOPB	LMZ12010TZ/NOPB	LMZ14203EXTTZE/NOPB	LMZ23608TZ/NOPB
LMZ10505EXTTZ/NOPB	LMZ12010TZE/NOPB	LMZ14203EXTTZ/NOPB	LMZ23608TZE/NOPB
LMZ10505TZ-ADJ/NOPB	LMZ13608TZ/NOPB	LMZ14203HTZ/NOPB	LMZ23610TZ/NOPB
LMZ10505TZE-ADJ/NOPB	LMZ13608TZE/NOPB	LMZ14203HTZ/NOPB	LMZ23610TZE/NOPB
LMZ10505TZ-ADJ/NOPB	LMZ13610TZ/NOPB	LMZ14203HTZ/NOPB	WPMDH1102401JT/NOPB
LMZ12001EXTTZ/NOPB	LMZ13610TZE/NOPB	LMZ14203TZ-ADJ/NOPB	WPMDH1152401JT/NOPB
LMZ12001EXTTZE/NOPB	LMZ14201EXTTZ/NOPB	LMZ14203TZE-ADJ/NOPB	WPMDH1200601JT/NOPB
LMZ12001EXTTZ/NOPB	LMZ14201EXTTZE/NOPB	LMZ14203TZ-ADJ/NOPB	WPMDH1302401JT/NOPB
LMZ12001TZ-ADJ/NOPB	LMZ14201EXTTZ/NOPB	LMZ14203TZADJ/UY8	WPMDM1500602JT/NOPB
LMZ12001TZE-ADJ/NOPB	LMZ14201HTZ/NOPB	LMZ22003TZ/NOPB	
LMZ12001TZ-ADJ/NOPB	LMZ14201HTZ/NOPB	LMZ22003TZE/NOPB	
LMZ12002EXTTZ/NOPB	LMZ14201HTZ/NOPB	LMZ22003TZ/NOPB	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com